

# Corres. and Mail BOX AF

PATENT \*\*//
Ser. No. 09/581,663
Atty. Docket No. 10191/1466

RESPONSE UNDER 37 C.F.R. 1.116
-EXPEDITED PROCEDURE -EXAMINING GROUP 1746

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Applicants** 

Volker BECKER et al.

Serial No.

09/581,663

Filed

August 3, 2000

For

METHOD FOR PROCESSING SILICON

BY ETCHING PROCESSES

OCT 1 7 2002 **TC 1700** 

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Group Art Unit

1765

Examiner

S. AHMED

Confirmation No.

4295

**BOX AF** 

COMMISSIONER FOR PATENTS

Washington D.C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: BOX AF, Commissioner for Patents, Washington, D.C. 20231 on

Date: October 7, 2002

Reg. No. 36,197

Signature:\_\_\_\_

Jong H. Lee

### **AMENDMENT UNDER 37 C.F.R. § 1.116**

Sir:

In response to the Final Office Action mailed July 5, 2002, the Applicants respectfully submit the following amendments and remarks. The Applicants respectfully assert that the Requested Amendments shown below should be entered because they place the application in condition for allowance and do not raise new issues.

#### REQUESTED AMENDMENTS

### IN THE CLAIMS:

Please amend the claims as follows:

33. (Once Amended) A method for etching a silicon layered body, which has a first silicon layer (15) that is provided with an etching mask (10) for defining lateral recesses (21); work with a